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(54) COMPOSITION FOR EXPANDABLE HOT-MELT ADHESIVE

(57)Abstract:

PURPOSE: To provide the titled compsn. which has stable expanding properties, can be well-bonded even to uneven surfaces and exhibits an excellent sealing effect, by blending a specified surface-active compd. with a polyamide resin.

CONSTITUTION: A fluorine compd. such as an oligomer having a perfluoroalkyl group, a lipophilic group and a hydrophilic group or an organosilicon compd. having an ability (surface activity) capable of lowering the surface tension of a polyamide resin in a molten state, is used. 0.001W5pts.wt. said fluorine compd. or organosilicon compd. is blended with 100pts.wt. polyamide resin exhibiting fluidity at 100W250° C. In using said compsn., it is molten to introduce foam thereinto and to assume an expanded state, and then applied on (injected into) an adherend surface.

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